

# MECHANICAL CASE OUTLINE

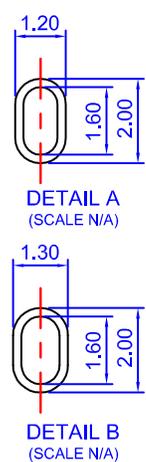
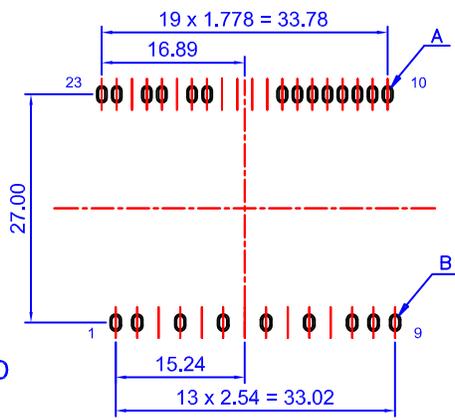
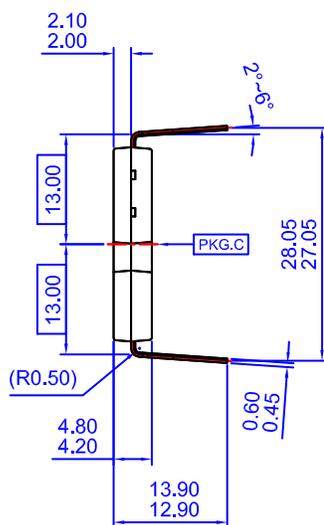
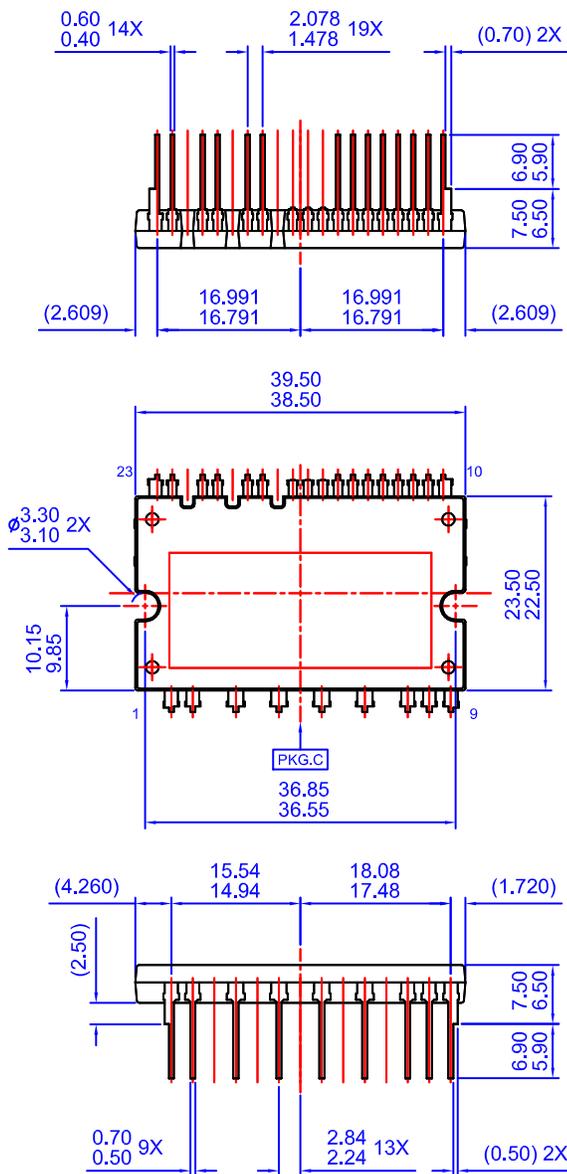
## PACKAGE DIMENSIONS

ON Semiconductor®



SPMAA-F26 / 23LD, SPM26-AAF (23LEAD), LONG LEAD, DUAL FORM STAND OFF OPTION 2.5MM  
CASE MODEV  
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DATE 31 JAN 2017



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  - B) ALL DIMENSIONS ARE IN MILLIMETERS
  - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
  - D) ( ) IS REFERENCE

### LAND PATTERN RECOMMENDATIONS

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